



Model : MBA27002 Series

BGA Heat Sink For 27x27 Chip set

Specification:

1. Material:

Heat Sink : CU1100

Clip : Plastic (UL94-V0)

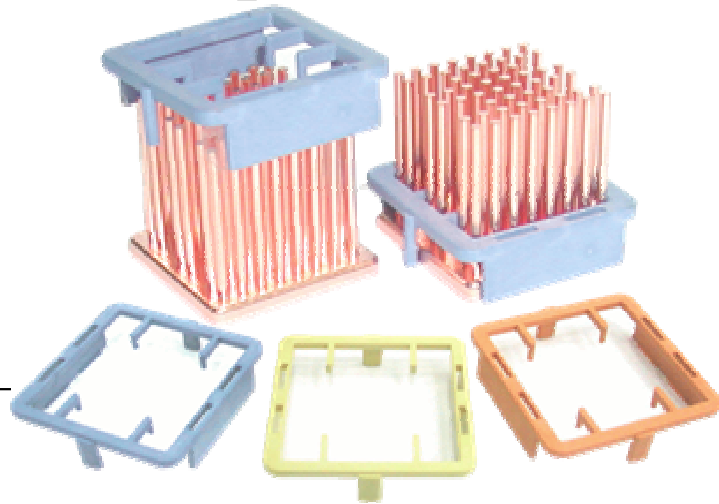
2. Heat sink dimension :

Foot print : 27x27mm

Part no.	Height	Fin shape	Base	Clip	Weight
MBA27002-	12	P	/2.6	- Y, BU, O	27.9g
MBA27002-	15	P	/2.6	- Y, BU, O	30.9g
MBA27002-	20	P	/2.6	- Y, BU, O	35.9g
MBA27002-	25	P	/2.6	- Y, BU, O	40.9g

3. Technology: Precision Forging

4. Finish: Oxygenless Treatment



5. Clip available:

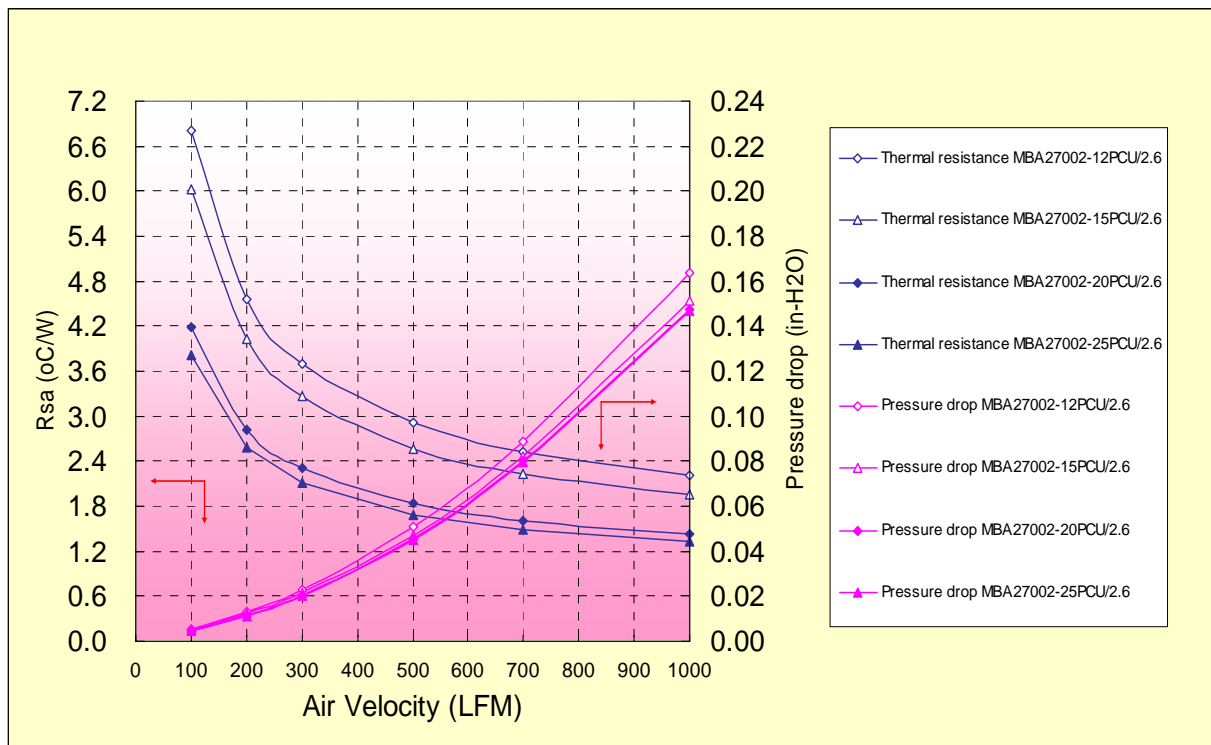
Chip set thickness

3.0-3.6mm **Y** - Yellow colored clip

1.4-2.0mm **BU** - Blue colored clip

0.5-1.1mm **O** - Orange colored clip

Performance Data:



Heat Source Size : Uniform



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